

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

THEODORE W. HOUSTON

Serial No. 09/346,436 (TI-21004)

Filed July 1, 1999

For: BONDED SOI WITH BURIED INTERCONNECT TO HANDLE OR DEVICE WAFER

Art Unit 2813

Examiner E. Kielin

Commissioner for Patents
Washington, D. C. 20231

Sir:



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McNellon
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AMENDMENT UNDER 37 C.F.R. 1.116

In response to the Office action dated January 22, 2001, please amend the above-identified application as follows:

In the claims:

Amend claim 1 as follows:

1. (Twice Amended) A method of fabricating an SOI structure which comprises the steps

of:

(a) providing a substrate having at least one of active or passive elements on a surface thereof and a device wafer having at least one of active or passive elements on a surface thereof;

(b) forming an electrically insulating layer having a pair of opposed outer faces, one of said outer faces disposed on said surface of one of said substrate or said device wafer, said

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